

11. Package Outline Drawing

The package outline drawing is located at the end of this document and is accessible from the Renesas website. The package information is the most current data available and is subject to change without revision of this document.

12. Ordering Information

Part Number ^{[1][2]}	Part Marking	Package Description ^[3] (RoHS Compliant)	Pkg. Dwg #	Carrier Type ^[4]	Temp. Range		
RAA489118ARGNP#AA0	489118 ARGNPA	32 Ld 4x4 TQFN	L32.4x4D	Tray	-10 to +100°C		
RAA489118ARGNP#HA0				Reel, 6k			
RAA489118A3GNP#AA0	489118 A3GNPA			Tray	-40 to +105°C		
RAA489118A3GNP#HA0				Reel, 6k			
RAA489118A3GNP#MA0				Reel, 1k			
RTKA489118DE0000BU	RAA489118 Evaluation Board - No BFET						
RTKA489118DE0010BU	RAA489118 Evaluation Board - with BFET						

- These Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J-STD-020.
- For the Moisture Sensitivity Level (MSL) see the [RAA489118](#) product page. For more information about MSL, see [TB363](#).
- For the Pb-Free Reflow Profile, see [TB493](#).
- See [TB347](#) for details about reel specifications.

13. Revision History

Revision	Date	Description
2.00	Oct 28, 2025	In section 3.3 Thermal Specifications, updated the values for the Thermal Resistance parameter.
1.03	Aug 21, 2025	Updated the waveforms in Figures 10, 11, 21, and 22. Updated Operation Mode values in Figure 39. Updated POD L32.4x4D to the latest version.
1.02	Jan 17, 2025	Added RAA489118A3GNP#MA0 to the Ordering Information and the PCB ECAD Design Information.
1.01	Oct 24, 2024	Updated POD L32.4x4D to the latest version. Added PCB ECAD Design Information.
1.00	Aug 9, 2024	Initial release